

8英寸全自动减薄设备

8 INCH FULLY-AUTOMATIC GRINDER

AG6800

- **最大有效加工尺寸 (mm)**
Maximum effective product size (mm)

Max. $\phi 200$ ($\phi 4'' \sim \phi 8''$)

- **主轴配置方式**
Configuration method of spindle

双主轴
Dual-spindle



● **特点** FEATURE

成熟稳定的加工过程。
Mature and stable processing.

IN-FEED主轴进给式磨削加工，加工精度高。
In-Feed spindle feed type High precision grinding.

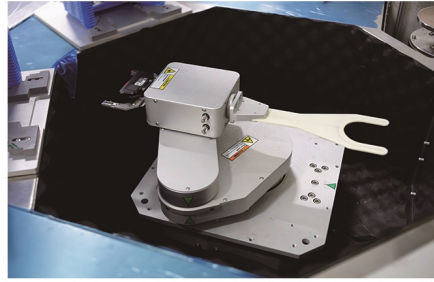
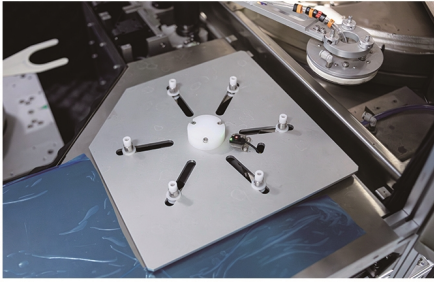
全自动流程错误处理，异常快速复机。
Automatic Process Error Handling, Rapid Recovery from Abnormalities.

全自动上下料与传输定位，大大降低OP工作量。
Fully automatic loading and unloading with transfer positioning, greatly reducing OP workload.

便捷的操作与人机交互界面。
Convenient operation and human-machine interface.

多工位协同工作，加工效率高。
Multi-station collaborative work with high processing efficiency.

干进干出加工 (DRY-IN & DRY-OUT) ,表面光洁。
Dry-in & Dry-Out processing, smooth surface.



功能 FUNCTION

注: 「*」为选配功能, 支持个性化定制
PS: 「*」 is an optional feature that can be customized by the customer

超薄晶圆加工与搬运传输

Ultra-thin wafer processing and transport

晶圆工作台自动清洗

Automatic wafer bench cleaning

实时高精度接触式晶圆测厚

Real-time, high-precision contact wafer thickness measurement

水、气二流体清洗

Water, gas two-fluid cleaning

功能模块化&软件定制

Functional modularity & software customization

真空预警与真空管路去水

Vacuum warning and vacuum line de-watering

操作日志记录

Operation log record

4/5/6/8英寸晶圆兼容

4/5/6/8 inch wafer compatible

主轴水冷系统

Spindle water cooling system

全自动/半自动模式

Fully Automatic/Semi-Automatic Mode

参数 PARAMETER

主轴转速 (Rpm)	Spindle speed (Rpm)	1,000-6,000
真空吸台转速 (Rpm)	Vacuum suction table speed (Rpm)	0-300
Z轴最小位移量 (μm)	Minimum displacement of Z-axis (μm)	0.1
最大磨削厚度 (mm)	Maximum grinding thickness (mm)	0.8
晶片磨削厚度 (μm)	Wafer grinding thickness (μm)	≥100
厚度变化量 (μm)	Amount of thickness change (μm)	≤2
不同片之间厚度变化量 (μm)	Amount of thickness variation between different slices (μm)	≤±3
精加工面粗糙度	Roughness of finishing surface	Ra≤30nm(2000#)(该参数主要取决于磨轮)
磨削方式	Grinding method	全自动主轴进给式磨削 Fully automatic spindle-feed grinding
测高范围 (mm)	Height measurement range (mm)	0 - 0.8
晶盒配置	Crystalline box configuration	2
设备重量 (kg)	Weight (kg)	≈4,200
设备尺寸/W*D*H (mm)	Size / W*D*H (mm)	1,200*2,800*1,900

应用 APPLICATION

